

S/N 09/733,289

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiao-Chun Mu et al.

Examiner: DiLinh Nguyen

Serial No.: 09/733,289

Group Art Unit: 2814

Filed: December 8, 2000

Docket No.: 884.798US1

Title: Microelectronic Package Having an Integrated Heat
Sink and Build-Up Layers

Customer Number: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on May 2, 2006. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office action, thereby moving the deadline for response from August 2, 2006 to September 2, 2006.